



Product Change Notification

113291 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 113291 - 00
Change Title: Intel® Server System R1304GL4DS9
PCN 113291-00, Product Design
Update the System Rear Panel, add a Mylar
and a Plastic Block
Date of Publication: October 13, 2014

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material *:	October 28, 2014
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** Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.*

Description of Change to the Customer:

Intel is implementing the following changes on the Intel® Server System R1304GL4DS9:

1. Add a connection at the bottom of the RMM4 (Remote Management Module 4) slot to improve structure strength. See item 1 in the Figure One.
2. Update the one big center joint to two smaller joints so that the joints will not conflict with the LAN cable connector latch. See item 2 in the Figure One.

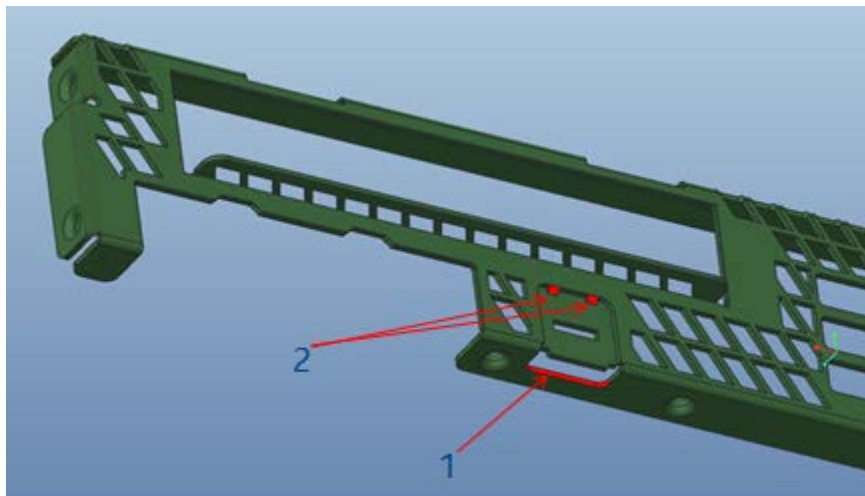


Figure One

3. Enlarge by 0.2mm at both the left and right sides of the rear panel to improve the flexibility. The previous width was 276.76mm and 274.27mm. The updated width is 277.16mm and 274.67mm. See the Figure Two.



Figure Two

4. Update the perf and add radius to improve structure strength. See the Figure Three and Four.

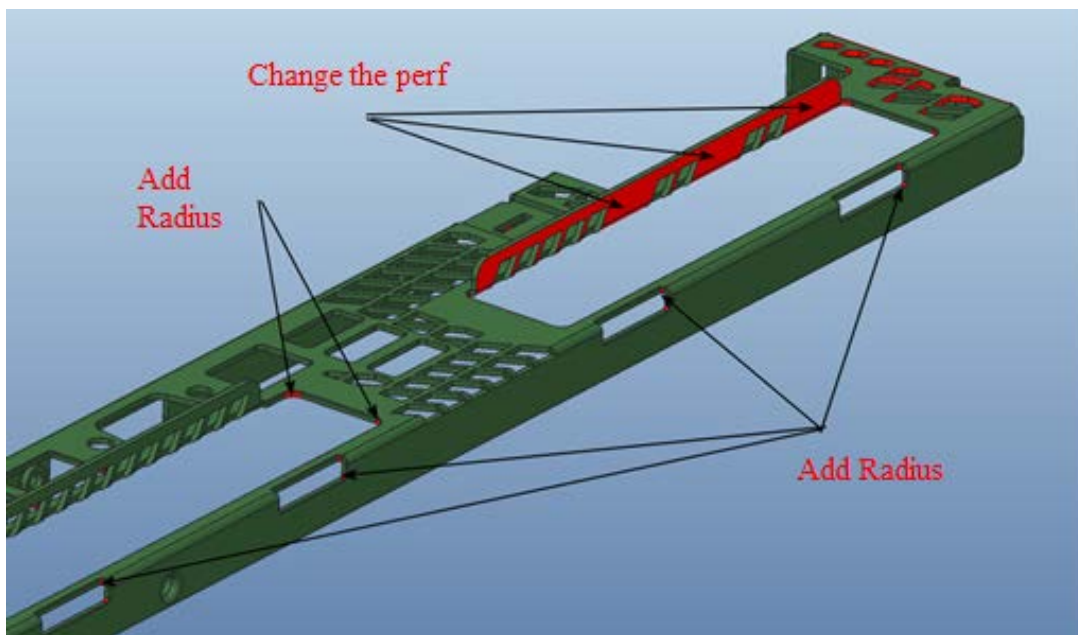


Figure Three

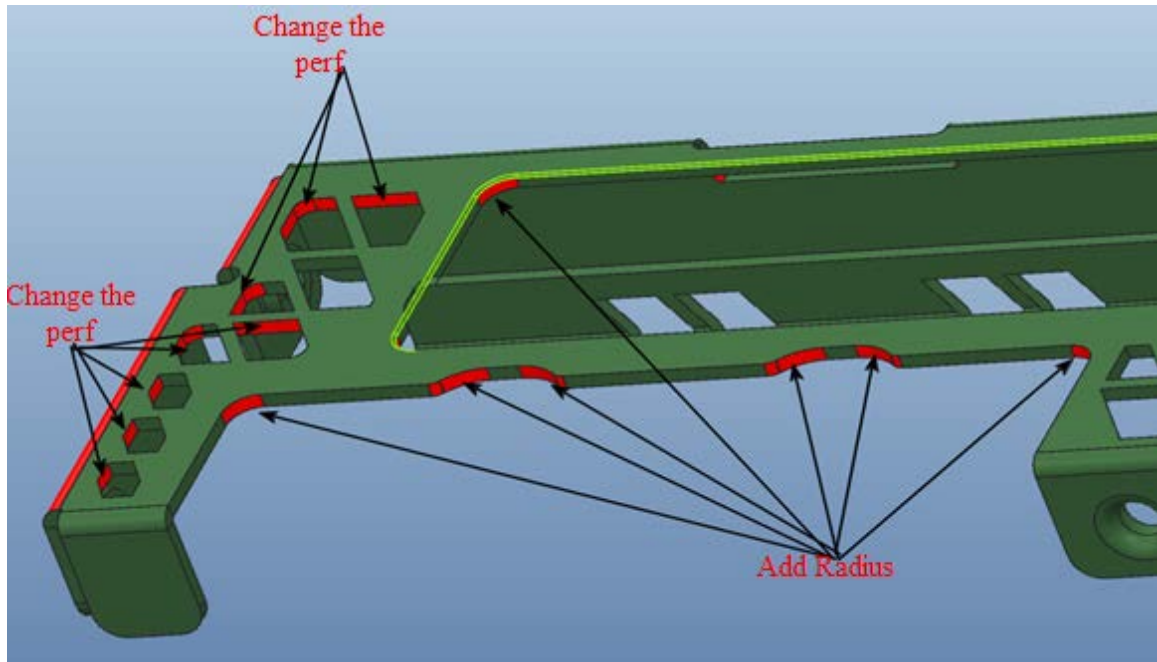


Figure Four

5. Add eight cut-offs around the on-board NIC (Network Interface Controller) openings to improve the LED visibility. See the Figure Five.

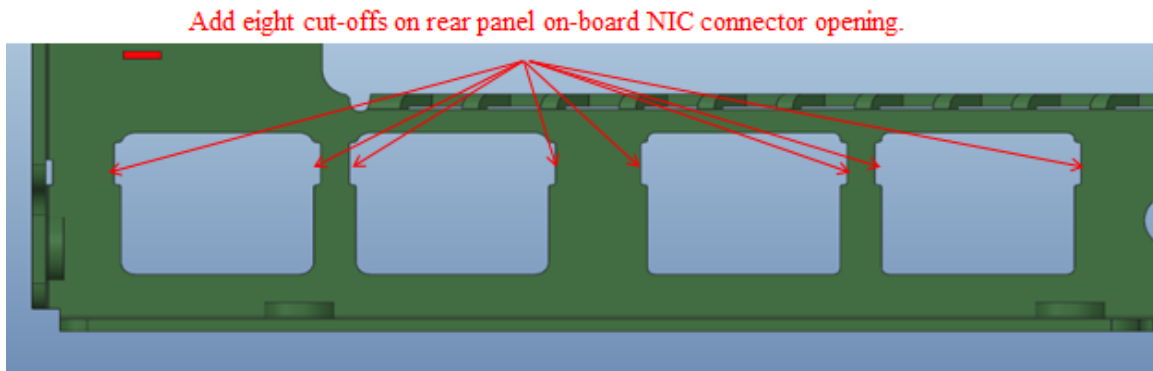
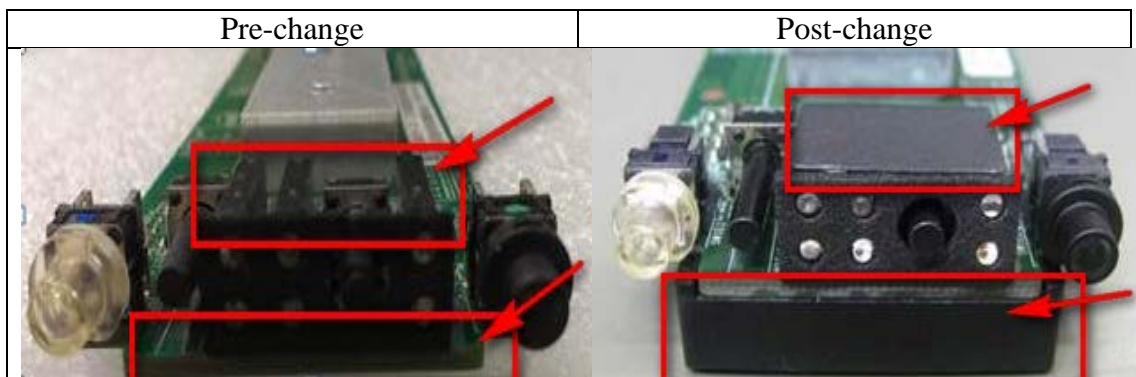


Figure Five

6. Add a mylar on the top of the front panel board and add a plastic block for the front end under the front panel board to hold parts more securely. See the images below:



Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes. Customers may need to validate the function and feature changes once the post-change system is available.

Products Affected / Intel Ordering Codes:

EMEA SKU			
Product Code	MM#	Pre Change TA	Post Change TA
R1304GL4DS9	922790	G67853-004	G67853-005

PCN Revision History:

Date of Revision:

October 13, 2014

Revision Number:

00

Reason:

Originally Published PCN